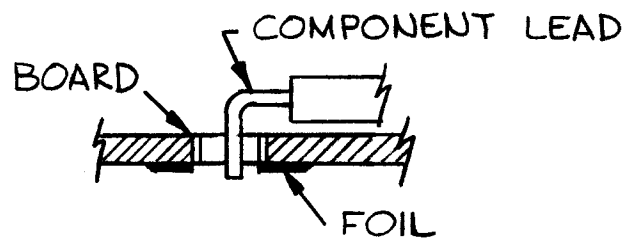
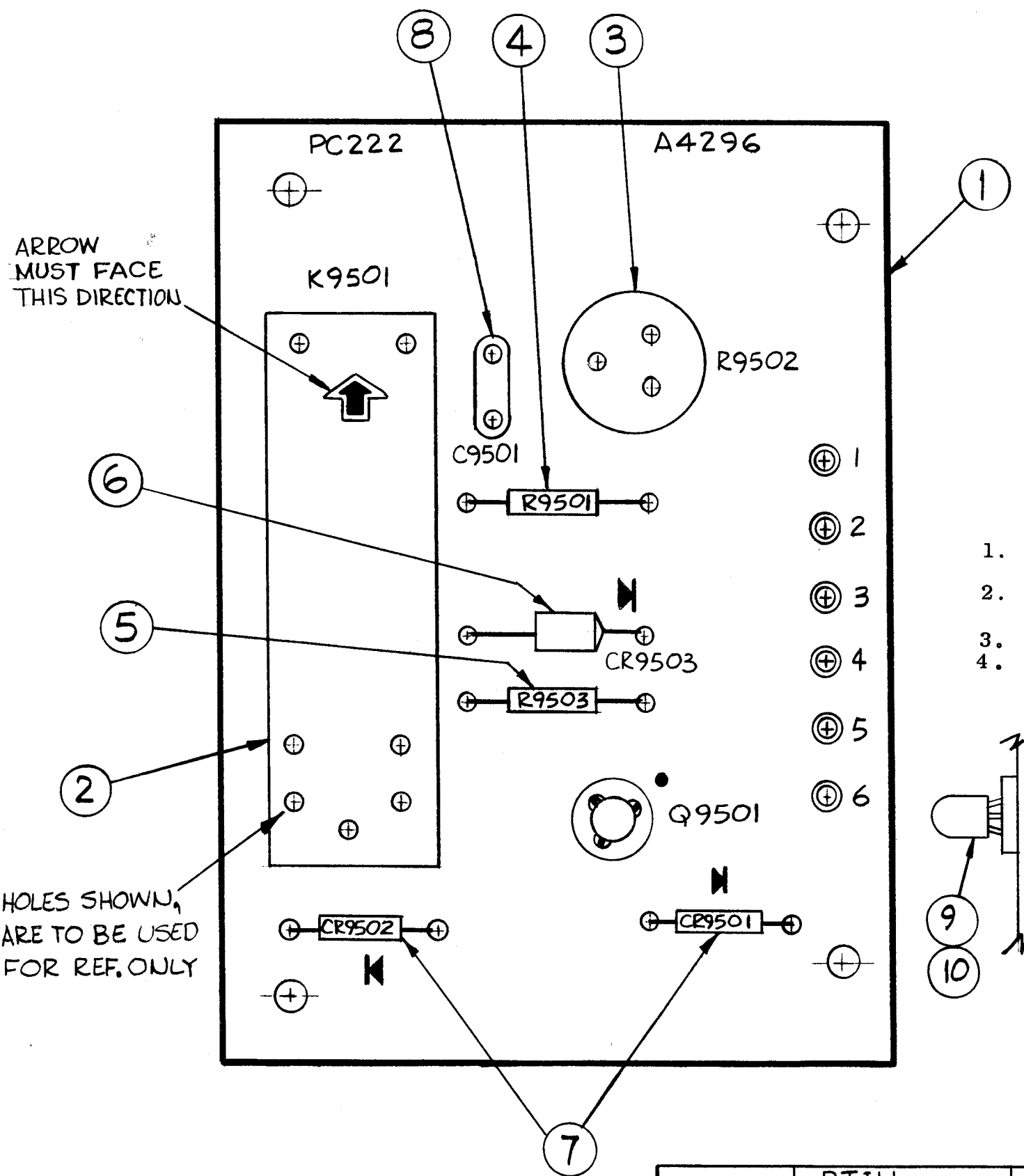


A4296

REVISIONS

SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD	APPD
X	EXPERIMENTAL RELEASE	5/25/66	X	CV		
Ø	ORIGINAL RELEASE FOR PRODUCTION	7/27/66	Ø	CV		JDE



ASSEMBLY NOTES

1. TO MOUNT COMPONENTS INSERT LEAD THROUGH HOLES & BEND ABOUT 1/16 OF LEAD OVER COPPER FOIL AS SHOWN.
2. APPLY HEAT & SOLDER TO LEAD & FOIL-CAUTION-TO MUCH HEAT WILL CAUSE THE FOIL TO SEPARATE FROM THE BOARD.
3. CLEAN AND INSPECT PER S676.
4. FUNGUS PROOFING PER TMC SPECIFICATION S113.

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
	11	BS100	SOLDER, TIN ALLOY	
1	10	PX829-5	PAD, TRANSISTOR MTG.	
1	9	2N3646	TRANSISTOR	Q9501
1	8	CM111F102J1S	CAP, FXD, MICA	CR9501
2	7	IN270	SCOND DEV, DIO	CR9501, CR9502
1	6	IN2484	SCOND DEV, DIO	CR9503
1	5	RC20GF273J	RES, FXD, COMP	R9503
1	4	RC20GF472J	RES, FXD, COMP	R9501
1	3	RV111U102A	RES, VARIABLE, COMP	R9502
1	2	RL167-1	RELAY, ARMATURE	R9501
1	1	PC222	PRINTED CIRCUIT BOARD	

EATON

LIST OF MATERIAL

MATERIAL	THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK			
FINISH	TITLE ASS'Y, PRINTED CIRCUIT BD.			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES	DRAWN R. UZZO	DATE 5-24-66	FINAL APPROVAL <i>[Signature]</i>	DATE 5/25/66
DECIMALS .X ± .05 .XX ± .01 .XXX ± .005	TOLERANCES	FRACTIONS ± 1/64 ANGLES ± 0° 30'	ELECT. DES. <i>[Signature]</i>	DATE 5/25/66
			MECH. DES.	DATE
			SHEET	REV. LIT.

RTIH	
Q'TY./UNIT	MODEL USED ON
SCALE 2:1	ASS'Y. NO.
CODE	
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NOTES